

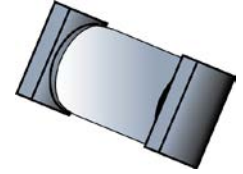


Voidless Hermetically Sealed Surface Mount Bidirectional Transient Voltage Suppressors
 Qualified to MIL-PRF-19500/516

Qualified Levels:
 JAN, JANTX, JANTXV
 and JANS*

DESCRIPTION

This surface mount series of industry recognized voidless, hermetically sealed, bidirectional Transient Voltage Suppressors (TVS) designs is military qualified to MIL-PRF-19500/516 and is ideal for high-reliability applications where a failure cannot be tolerated. They provide a Working Peak “Standoff” Voltage selection from 5.7 to 152 Volts with a 500 W rating for a 10/1000 μ s pulse. They are very robust in hard-glass construction and internal “Category 1” metallurgical bonds. These are also available as both a non-suffix part and an “A” version providing different voltage tolerances as described in the nomenclature section. These devices are also available in axial-leaded packages for thru-hole mounting.



“B” or SQ-MELF Package

Important: For the latest information, visit our website <http://www.microsemi.com>.

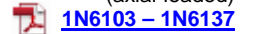
Also available in:

FEATURES

- High surge current and peak pulse power provides transient voltage protection for sensitive circuits.
- Triple-layer passivation.
- Internal “Category 1” metallurgical bonds.
- Voidless hermetically sealed glass package.
- JAN, JANTX, and JANTXV qualified versions are available per MIL-PRF-19500/516.
- *JANS available for 1N6103(A)US thru 1N6118(A)US per MIL-PRF-19500/516 as well as further options for screening in reference to MIL-PRF-19500 for all others in this series. (See [part nomenclature](#) for all available options.)
- RoHS compliant versions available (commercial grade only).

“B” Package

(axial-leaded)



APPLICATIONS / BENEFITS

- Military and other high-reliability applications.
- Extremely robust construction.
- Extensive range in working peak “standoff” voltage (V_{WM}) from 5.7 to 152 volts.
- 500 watt peak pulse power (P_{PP}) for a 10/1000 μ s pulse.
- ESD and EFT protection per IEC6100-4-2 and IEC61000-4-4 respectively.
- Protection from the secondary effects of lightning per select levels in IEC61000-4-5.
- Square-end-cap terminals for easy placement.
- Non-sensitive to ESD per MIL-STD-750 method 1020.
- Inherently radiation hard as described in Microsemi “[MicroNote 050](#)”.

MAXIMUM RATINGS @ $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T_J and T_{STG}	-55 to +175	$^\circ\text{C}$
Thermal Resistance Junction-to-End Cap	$R_{\theta JEC}$	8.3	$^\circ\text{C/W}$
Peak Pulse Power @ 25°C (10/1000 μ s)	P_{PP}	500	W
Steady-State Power up to $T_{EC} = 150^\circ\text{C}$ ⁽¹⁾	P_D	3.0	W
Steady-State Power @ $T_A = 25^\circ\text{C}$ ⁽²⁾	P_D	2.0	W
Impulse Repetition Rate	df	0.01	%
Solder Temperature @ 10 s	T_{SP}	260	$^\circ\text{C}$

- Notes:**
1. Linearly derate above $T_{EC} = 150^\circ\text{C}$ to zero at $T_{EC} = 175^\circ\text{C}$.
 2. Steady-state power ratings with reference to ambient are for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where maximum rated T_J is not exceeded (also see [figure 4](#)).

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MECHANICAL and PACKAGING

- CASE: Hermetically sealed voidless hard glass with tungsten slugs.
- TERMINALS: Tin/lead plate over copper. RoHS compliant matte-tin is available on commercial grade only.
- MARKING: None.
- POLARITY: No polarity marking for these bidirectional TVSs.
- TAPE & REEL option: Standard per EIA-481-B. Consult factory for quantities.
- WEIGHT: Approximately 539 milligrams.
- See [Package Dimensions](#) on last page.

PART NOMENCLATURE

Applicable to entire series:

JAN 1N6103 A US (e3)

Reliability Level

JAN = JAN Level
 JANTX = JANTX Level
 JANTXV = JANTXV Level
 Blank = commercial

JEDEC type number

See [Electrical Characteristics](#) table

RoHS Compliance

e3 = RoHS compliant (available on commercial grade only)
 Blank = non-RoHS compliant

Surface Mount Package

Voltage Tolerance

A = Standard
 Blank = 5% higher V_C , 5% lower min. $V_{(BR)}$ and 5% lower I_{PP}

Applicable to 1N6103(A)US – 1N6118(A)US only:

JANS 1N6103 A US

Reliability Level

JANS = JANS Level

JEDEC type number

See [Electrical Characteristics](#) table

Surface Mount Package

Voltage Tolerance

A = Standard
 Blank = 5% higher V_C , 5% lower min. $V_{(BR)}$ and 5% lower I_{PP}

Applicable to 1N6119(A)US – 1N6137(A)US only:

MSP 1N6119 A US (e3)

Reliability Level

MSP (reference JANS)

JEDEC type number

See [Electrical Characteristics](#) table

RoHS Compliance

e3 = RoHS compliant
 Blank = non-RoHS compliant

Surface Mount Package

Voltage Tolerance

A = Standard
 Blank = 5% higher V_C , 5% lower min. $V_{(BR)}$ and 5% lower I_{PP}

SYMBOLS & DEFINITIONS

Symbol	Definition
$V_{(BR)}$	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.
V_{WM}	Working Peak Voltage: The maximum peak voltage that can be applied over the operating temperature range. This is also referred to as Standoff Voltage.
I_D	Maximum Standoff Current: The maximum current that will flow at the specified voltage and temperature.
V_C	Maximum clamping voltage at specified I_{PP} (Peak Pulse Current) at the specified pulse conditions.
P_{PP}	Peak Pulse Power: The peak power dissipation resulting from the peak impulse current I_{PP} .

ELECTRICAL CHARACTERISTICS

INDUSTRY TYPE NUMBER (Note 1)	MINIMUM BREAKDOWN VOLTAGE (Note 1)		RATED STANDOFF VOLTAGE	MAXIMUM STANDBY CURRENT	MAXIMUM CLAMPING VOLTAGE (Note 1)	MAXIMUM PEAK PULSE CURRENT (Note 1)	MAXIMUM TEMP. COEF. OF $V_{(BR)}$
	$V_{(BR)}$	@ $I_{(BR)}$	V_{WM}	I_D @ V_{WM}	V_C @ I_{PP}	I_{PP}	$\alpha_{V(BR)}$
	Volts	mA	V	μA	Volts	Amps	%/°C
†1N6103AUS	7.13	175	5.7	50	11.2	44.6	.06
†1N6104AUS	7.79	150	6.2	20	12.1	41.3	.06
†1N6105AUS	8.65	150	6.9	20	13.4	37.3	.06
†1N6106AUS	9.50	125	7.6	20	14.5	34.5	.07
†1N6107AUS	10.45	125	8.4	20	15.6	32.0	.07
†1N6108AUS	11.40	100	9.1	20	16.9	29.6	.07
†1N6109AUS	12.35	100	9.9	20	18.2	27.5	.08
†1N6110AUS	14.25	75	11.4	20	21.0	23.8	.08
†1N6111AUS	15.20	75	12.2	20	22.3	22.4	.08
†1N6112AUS	17.10	65	13.7	1	25.1	19.9	.085
†1N6113AUS	19.0	65	15.2	1	27.7	18.0	.085
†1N6114AUS	20.9	50	16.7	1	30.5	16.4	.085
†1N6115AUS	22.8	50	18.2	1	33.3	15.0	.09
†1N6116AUS	25.7	50	20.6	1	37.4	13.4	.09
†1N6117AUS	28.5	40	22.8	1	41.6	12.0	.09
†1N6118AUS	31.4	40	25.1	1	45.7	10.9	.095
1N6119AUS	34.2	30	27.4	1	49.9	10.0	.095
1N6120AUS	37.1	30	29.7	1	53.6	9.3	.095
1N6121AUS	40.9	30	32.7	1	59.1	8.5	.095
1N6122AUS	44.7	25	35.8	1	64.6	7.7	.095
1N6123AUS	48.5	25	38.8	1	70.1	7.1	.095
1N6124AUS	53.2	20	42.6	1	77.0	6.5	.095
1N6125AUS	58.9	20	47.1	1	85.3	5.9	.100
1N6126AUS	64.6	20	51.7	1	97.1	5.1	.100
1N6127AUS	71.3	20	56.0	1	103.1	4.8	.100
1N6128AUS	77.9	15	62.2	1	112.8	4.4	.100
1N6129AUS	86.5	15	69.2	1	125.1	4.0	.100
1N6130AUS	95.0	12	76.0	1	137.6	3.6	.100
1N6131AUS	104.5	12	86.6	1	151.3	3.3	.100
1N6132AUS	114.0	10	91.2	1	165.1	3.0	.100
1N6133AUS	123.5	10	98.8	1	178.8	2.8	.105
1N6134AUS	142.5	8	114.0	1	206.3	2.4	.105
1N6135AUS	152.0	8	121.6	1	218.4	2.3	.105
1N6136AUS	171.0	5	136.8	1	245.7	2.0	.110
1N6137AUS	190.0	5	152.0	1	273.0	1.8	.110

† Also available in JANS qualification per MIL-PRF-19500/516.

Notes: 1. Part number without the A suffix has 5% higher V_C , 5% lower minimum $V_{(BR)}$, and 5% lower I_{PP} .

GRAPHS

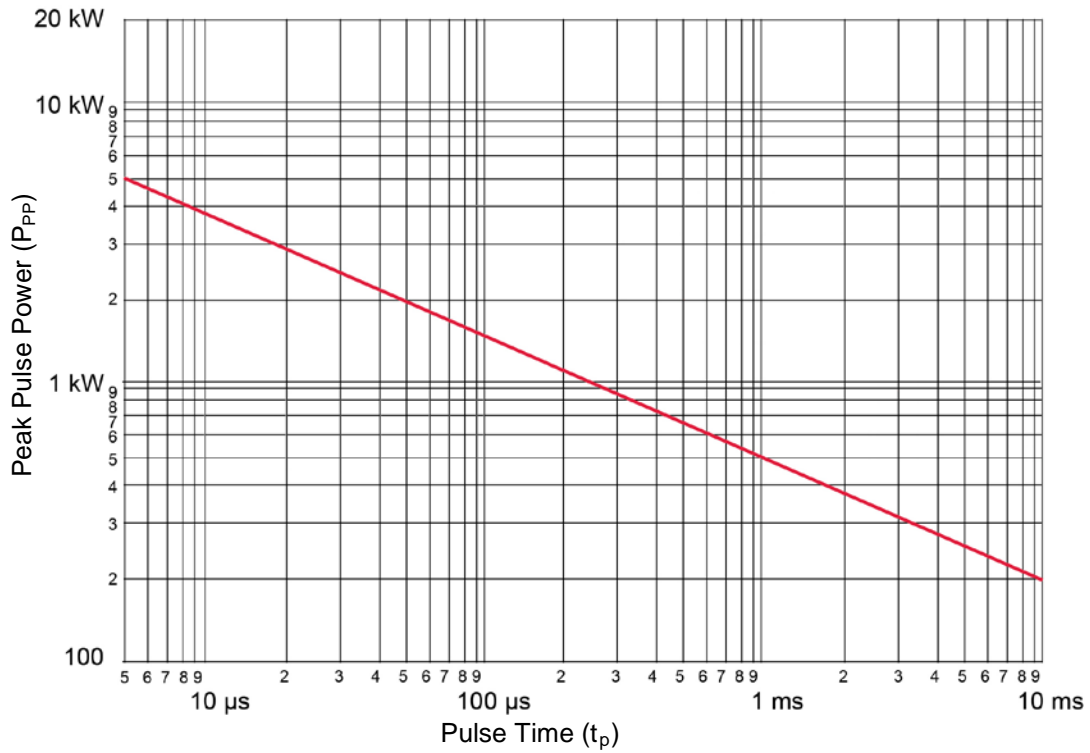


FIGURE 1
Peak Pulse Power vs. Pulse Time



FIGURE 2
Peak Pulse Power vs T_J (prior to impulse)

GRAPHS



FIGURE 3
Pulse Wave Form



FIGURE 4
Temperature-Power Derating Curve

PACKAGE DIMENSIONS


Ltr	Dimensions				Notes
	Inch		Millimeters		
	Min	Max	Min	Max	
BD	0.137	0.148	3.48	3.76	
BL	0.200	0.225	5.08	5.72	
ECT	0.019	0.028	0.48	0.71	
S	0.003	-	0.08	-	4

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. Minimum clearance of glass body to mounting surface on all orientations.
4. In accordance with ASME Y14.5M, diameters are equivalent to Φ x symbology.

PAD LAYOUT


DIM	INCH	MILLIMETERS
A1	0.288	7.32
A2	0.144	3.66
B	0.070	1.78
C	0.155	3.94

NOTE: If mounting requires adhesive separate from the solder, an additional 0.080 inch (2.03 mm) diameter contact may be placed in the center between the pads as an optional spot for cement.